

Processing facilities:

- 1. Electron beam lithography (e-line plus from RAITH GmbH).*
- 2. Maskless lithography system , Mask Aligner (MA6 from Suss Microtec Gmb).*
- 3. Electron beam evaporation system and RF sputtering system.*
- 4. Plasma enhanced chemical vapour deposition (PECVD, Reactive ion etching (RIE) and Inductively coupled plasma (ICP)-RIE systems.*
- 5. Wet benches for chemical cleaning and etching*